

Amendments to the Specification

On page 1 of the specification, please replace the paragraph following the heading “RELATED PATENT APPLICATION” with the following paragraph:

“This application is related to [the following: Docket #TS03-346,] U.S. Patent Application Ser. No. 10/987,713 [] , filed on 11/12/2004, [] which is assigned to a common assignee.”

On pages 14-15 of the specification, please replace the paragraph beginning “Referring to FIG. 5 ...” with the following paragraph:

“Referring to FIG. 5, a second ECP process is performed to deposit a second metal layer **19** that is preferably copper on the first metal layer **18**. In one embodiment, the second ECP process is performed in a second work piece with an electrolyte solution that does not contain HCl or a carbon based additive as described in the related ~~TSMC~~ U.S. patent application Ser. No. 10/987,713, filed 11/12/2004~~TS03-346~~, herein incorporated by reference, and thereby avoids incorporating Cl and C contaminants in the second metal layer **19**. Preferably, the second ECP process involves the same electrolyte solution and work piece that was employed in the first ECP process. The second ECP process is performed at a temperature of 10°C to 20°C and is comprised of two steps. The first step has a second current density of about 20 to 60 mA/cm² and preferably 40 mA/cm² that is applied until the second metal layer **19** fills the trench **15**. This first step of the second ECP process is referred to by the inventors as ECP I40 and is continued for a period of about 30 to 50 seconds and has a metal deposition rate of about 150 Angstroms per minute.”